

DS-11

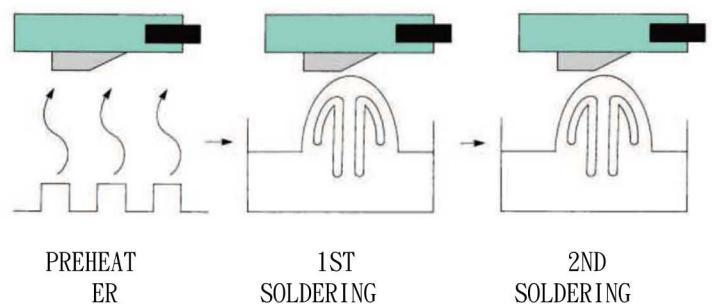
DIP TESTER



- Long Seller for production management of Flow Soldering has been renewed.
- Dedicated software realizes high level management, USB communication to a PC, Creating Profile function & etc.
- Cooling stand included for quick cooling and sensor protection.

Model : DS-11

- USB connection to a PC, the dedicated software enables for OK/NG judgment and management of the test results.
- The created temperature profile makes it possible to monitor 0.1s sampling temperature of the preheat and solder temperature sensors in addition to the conventional management items.
- The heat-resistant cover for high heat load such as Nitrogen oven and etc. is available as an option.
- Protecting the sensor part after measurement is attached stand with cooling function.



Measurement Data Specifications

Items	Sensor	Display	Measurement Range	Accuracy
PC board back surface temp.	K-type thermocouple	LCD digital 3-digit	0~300℃	±1℃
Solder temp.	K-type sheath thermocouple		0~300℃	±1℃
Dip time	Electrode (4pcs.)		0~10.0sec.	±0.2sec.

General Specifications

Items	
Cold contact point compensation	Compensation with platinum temp. measuring resistor
Ambient temp.	5 minutes max. at 150℃
Battery	AAA batteries x 2pcs.
External connection	USB (type A – type C)
Number of memory	1 data
Sampling time	0.1sec. (fix)
Outer dimensions	78 (W) x 214 (D) x 43.6 (H) mm
Weight	Approx. 820g (batteries are not included)

* The above specifications are subject to change without notice.

Soldering Process Devices
LED Manufacturing Devices

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